

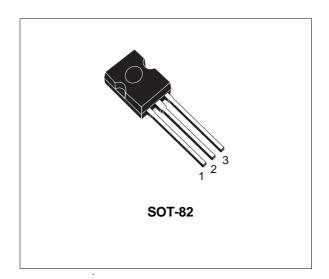
# BULK128D-B

# HIGH VOLTAGE FAST-SWITCHING NPN POWER TRANSISTOR

- STMicroelectronics PREFERRED SALESTYPE
- INTEGRATED ANTIPARALLEL COLLECTOR-EMITTER DIODE
- NPN TRANSISTOR
- HIGH VOLTAGE CAPABILITY
- LOW SPREAD OF DYNAMIC PARAMETERS
- MINIMUM LOT-TO-LOT SPREAD FOR RELIABLE OPERATION
- VERY HIGH SWITCHING SPEED

#### **APPLICATIONS:**

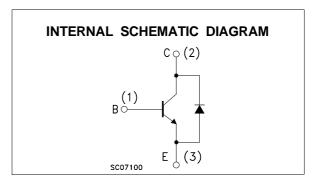
- ELECTRONIC BALLASTS FOR FLUORESCENT LIGHTING
- FLYBACK AND FORWARD SINGLE TRANSISTOR LOW POWER CONVERTERS



#### **DESCRIPTION**

The device is manufactured using high voltage Multi Epitaxial Planar technology for high switching speeds and medium voltage capability. It uses a Cellular Emitter structure with planar edge termination to enhance switching speeds while maintaining the wide RBSOA.

The device is designed for use in lighting applications and low cost switch-mode power supplies.



#### **ABSOLUTE MAXIMUM RATINGS**

Symbol	Parameter	Value	Unit
V <sub>CES</sub>	Collector-Emitter Voltage (V <sub>BE</sub> = 0)	700	V
Vceo	Collector-Emitter Voltage (I <sub>B</sub> = 0)	400	V
V <sub>EBO</sub>	Emitter-Base Voltage	BV <sub>EBO</sub>	V
	$(I_C = 0, I_B = 2 A, t_p < 10 \mu s, T_j < 150 ^{\circ}C)$		
Ic	Collector Current	4	Α
I <sub>CM</sub>	Collector Peak Current (tp < 5 ms)	8	Α
lΒ	Base Current	2	Α
I <sub>BM</sub>	Base Peak Current (t <sub>p</sub> < 5 ms)	4	А
P <sub>tot</sub>	Total Dissipation at T <sub>c</sub> = 25 °C	55	W
T <sub>stg</sub>	Storage Temperature	-65 to 150	°C
$T_j$	Max. Operating Junction Temperature	150	°C

August 2001 1/7

### THERMAL DATA

R <sub>thj-case</sub>	Thermal Resistance Junction-Case	Max	2.27	°C/W
$R_{thj-amb}$	Thermal Resistance Junction-Ambient	Max	80	°C/W

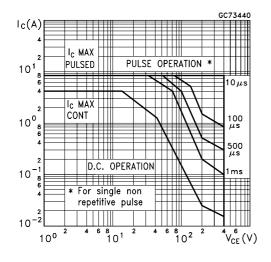
# **ELECTRICAL CHARACTERISTICS** (T<sub>case</sub> = 25 °C unless otherwise specified)

Symbol	Parameter	Test (	Conditions	Min. Typ.		Max.	Unit
I <sub>CES</sub>	Collector Cut-off Current (V <sub>BE</sub> = -1.5 V)	V <sub>CE</sub> = 700 V V <sub>CE</sub> = 700 V	T <sub>C</sub> = 125 °C			100 500	μA μA
I <sub>CEO</sub>	Collector-Emitter Leakage Current (I <sub>B</sub> = 0)	V <sub>CE</sub> = 400 V				250	μА
BV <sub>EBO</sub>	Emitter-Base Breakdown Voltage (I <sub>C</sub> = 0)	I <sub>E</sub> = 10 mA		9		18	V
$V_{\text{CEO(sus)}}^*$	Collector-Emitter Sustaining Voltage (I <sub>B</sub> = 0)	I <sub>C</sub> = 100 mA	L = 25 mH	400			V
V <sub>CE(sat)</sub> *	Collector-Emitter Saturation Voltage	$I_{C} = 0.5 A$ $I_{C} = 1 A$ $I_{C} = 2.5 A$	$I_B = 0.1 A$ $I_B = 0.2 A$ $I_B = 0.5 A$			0.7 1 1.5	V V V
V <sub>BE(sat)</sub> *	Base-Emitter Saturation Voltage	I <sub>C</sub> = 0.5 A I <sub>C</sub> = 1 A I <sub>C</sub> = 2.5 A	I <sub>B</sub> = 0.1 A I <sub>B</sub> = 0.2 A I <sub>B</sub> = 0.5 A			1.1 1.2 1.3	V V V
h <sub>FE</sub> *	DC Current Gain	I <sub>C</sub> = 10 mA I <sub>C</sub> = 2 A	V <sub>CE</sub> = 5 V V <sub>CE</sub> = 5 V	10 8		40	
$V_{f}$	Forward Voltage Drop	I <sub>f</sub> = 2 A				2.5	V
t <sub>s</sub>	RESISTIVE LOAD Storage Time Fall Time	$V_{CC} = 250 \text{ V}$ $I_{B1} = 0.4 \text{ A}$ $T_p = 30  \mu\text{s}$	$I_C = 2 A$ $I_{B2} = -0.4 A$ (see fig. 2)	2	0.2	2.9	μs μs
t <sub>s</sub> t <sub>f</sub>	INDUCTIVE LOAD Storage Time Fall Time	$V_{CC} = 200 \text{ V}$ $I_{B1} = 0.4 \text{ A}$ $R_{BB} = 0 \Omega$ (see fig. 1)	I <sub>C</sub> = 2 A V <sub>BE(off)</sub> = -5 V L = 200 μH		0.6 0.1		μs μs

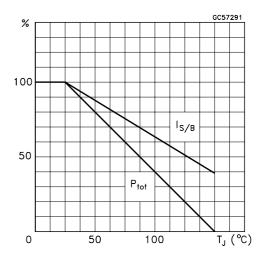
<sup>\*</sup> Pulsed: Pulse duration = 300 μs, duty cycle 1.5 %

2/7

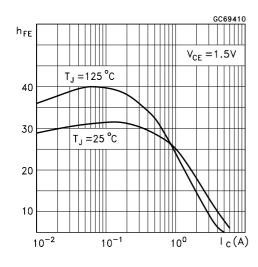
### Safe Operating Areas



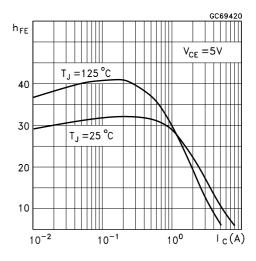
## **Derating Curve**



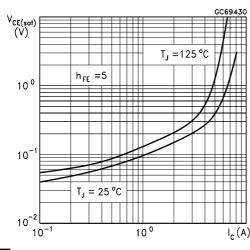
### DC Current Gain



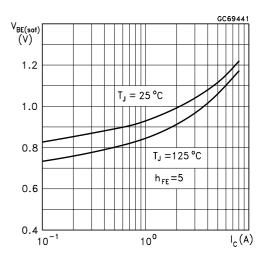
DC Current Gain



## Collector Emitter Saturation Voltage



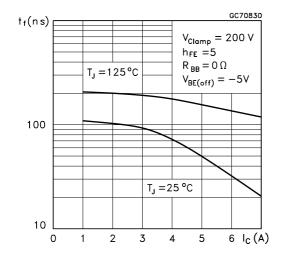
Base Emitter Saturation Voltage



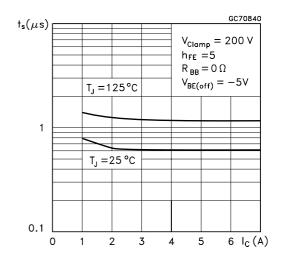
**477** 

#### BULK128D-B

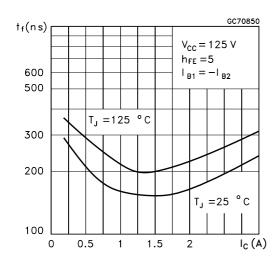
### Inductive Fall Time



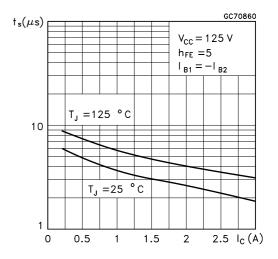
### Inductive Storage Time



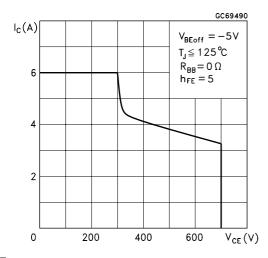
#### Resistive Load Fall Time



Resistive Load Storage Time



#### Reverse Biased SOA



4/7

Figure 1: Inductive Load Switching Test Circuit.

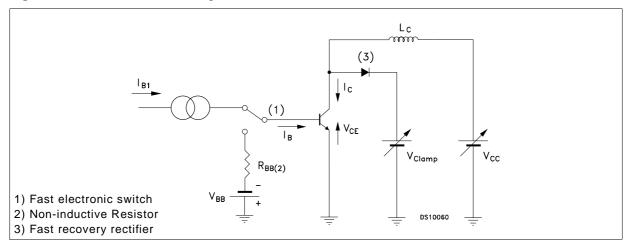
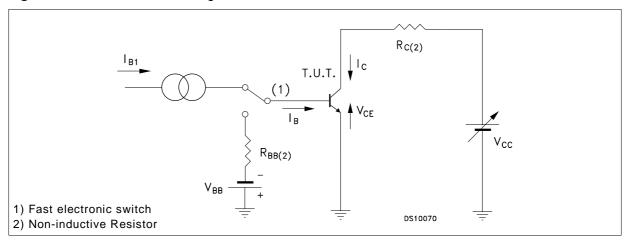
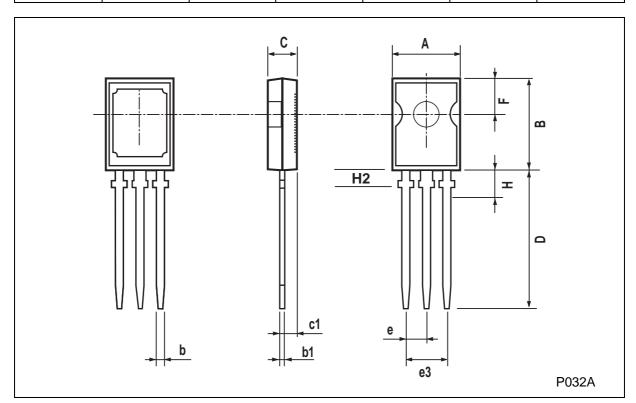


Figure 2: Resistive Load Switching Test Circuit.



## **SOT-82 MECHANICAL DATA**

DIM.	mm			inch			
Dini.	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.	
Α	7.4		7.8	0.291		0.307	
В	10.5		10.8	0.413		0.444	
b	0.7		0.9	0.028		0.035	
b1	0.49		0.75	0.019		0.030	
С	2.4		2.7	0.04		0.106	
c1	1.0		1.3	0.039		0.05	
D	15.4		16	0.606		0.629	
е		2.2			0.087		
e3	4.15		4.65	0.163		0.183	
F		3.8			0.150		
Н			2.54		0.100		
H2		2.15			0.084		



6/7

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